

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application

**Listing of Claims:**

1-11 (cancelled)

12. (currently amended) The method according to Claim ~~[[10]]~~ 18, further comprising the step of attaching solder balls to said second surface of said patterned metal layer exposed in said windows in said second insulating layer.

13. (cancelled)

14. (currently amended) The method according to Claim ~~[[10]]~~ 18, wherein said step of removing said carrier tape is preceded by the step of exposing said carrier tape to ultra-violet radiation.

15. (currently amended) The method according to Claim ~~[[11]]~~ 18, wherein said step of applying a second insulating layer comprises applying less than 30  $\mu\text{m}$  of insulating layer to said second surface of said patterned metal layer.

16. (currently amended) The method according to Claim ~~[[11]]~~ 18, wherein said step of applying a second insulating layer comprises applying solder resist to said second surface of said patterned metal layer.

17. (currently amended) The method according to Claim ~~[[10]]~~ 18, wherein said step of providing a substrate with a first insulating layer comprises providing a substrate with a solder resist layer covering said first surface of said patterned metal layer.

18. (previously presented)      A method for packaging an integrated circuit chip, comprising:

providing an integrated circuit chip;

providing an insulating carrier tape with a patterned metal layer with a first side adhering to the insulating carrier tape;

positioning the integrated circuit chip over a second side of the metal layer and electrically connecting the integrated circuit chip to the metal pattern;

encapsulating the chip and the electrical connections;

removing the carrier tape to uncover the entire first side of the metal layer; and

then applying an insulating layer to the first side uncovering a portion of the first side of the patterned metal layer.

19. (previously presented)      The method of claim 18, in which the insulating layer is thinner than the insulating carrier tape.